

Claims

1. Process for finishing a wood or wooden board, in particular an MDF or HDF
5 board with an upper side and an underside, comprising the following steps:
 - a) applying a sealing layer of melamine resin to the upper side of the board,
 - b) printing a decoration onto the sealing layer,
 - c) applying a protective layer of melamine resin to the decoration, and
 - d) pressing the board under the action of temperature until the protective layer
10 and the sealing layer melt and bend to each other with the inclusion of the decoration
printed thereon.
2. The process as claimed in claim 1, further comprising the following steps:
15 applying a sealing layer of melamine resin to the underside of the board,
applying a colored layer to the sealing layer on the upper side of the board,
applying the protective layer of melamine resin to the decoration, and
pressing the board under the action of temperature until the protective layer
and the sealing layer melt and bond to each other with the inclusion of the colored
layer.
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3. The process according to claim 1, wherein the upper side and the underside
are finished at the same time.
4. The process according to claim 1, wherein a plurality of individual layers are
25 applied for at least one of the sealing layer and the protective layer and each
individual layer dries out before the application of the next.
5. The process according to claim 2, wherein the board is ground before the
sealing layer is applied.
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6. The process according to claim 4, further comprising providing corundum into at least one individual layer of the protective layer.
7. The process according to claim 4, further comprising scattering corundum onto at least one individual layer of the protective layer.
8. The process according to claim 4, further comprising mixing at least one of antibacterial and antistatic additives into at least one individual layer of the protective layer.
9. The process according to claim 4, further comprising scattering at least one of antibacterial and antistatic additives onto at least one individual layer of the protective layer.
10. The process according to claim 1, further comprising providing at least one filler into at least one of a sealing layer and the protective layer.
11. The process according to claim 10, wherein the filler is wood fibers, wood dust, metals, mineral substances, plastics or ash.
12. The process according to claim 1, wherein finishing of the upper side of the board is carried out only in some regions.
13. The process according to claim 10, wherein finishing is carried out on an area running obliquely with respect to the upper side.
14. The process according to claim 1, wherein a structure or at least one V joint is impressed into the protective layer.
15. A wooden board comprising an HDF (high density fibreboard) or MDF (medium density fibreboard) substrate board with an upper side and an underside, the

upper side having a decoration, wherein a sealing layer onto which a decoration is printed is applied to the substrate board, and in that the decoration is covered by at least one wear-resistant layer.

5 16. The wooden board according to claim 15, wherein the sealing layer is formed of melamine or urea resin.

17. The wooden board according to claim 15, wherein the decoration is printed directly onto the sealing layer.

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18. The wooden board according to claim 15, wherein the decoration comprises heat-resistant colors.

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19. The wooden board according to claim 15, wherein the wear-resistant layer is a varnish layer.

20. The wooden board according to claim 19, wherein the varnish layer is electron-beam cured or UV cured.

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21. The wooden board according to claim 15, further comprising structuring means or corundum granules applied to the decoration in order to increase the abrasion resistance.

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22. The wooden board according to claim 19, further comprising structuring means or corundum granules embedded in the varnish layer.

23. The wooden board according to claim 15, wherein the substrate board is smooth on at least one of the upper side and underside.

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24. The wooden board according to claim 15, wherein the substrate board is ground on at least one of the upper side and underside.

25. The wooden board according to claim 15, further comprising a structure or at least one V joint embossed into the wear-resistant layer.